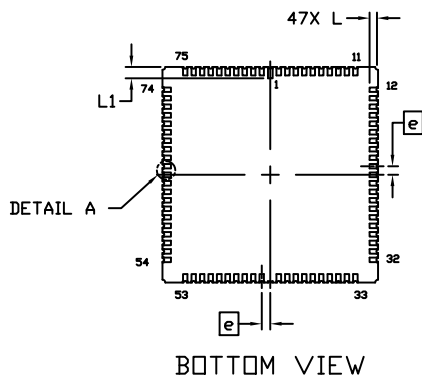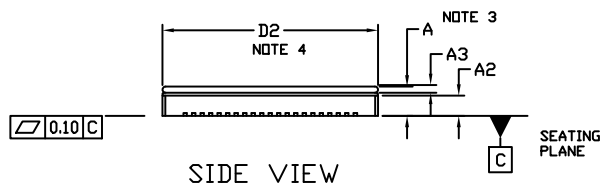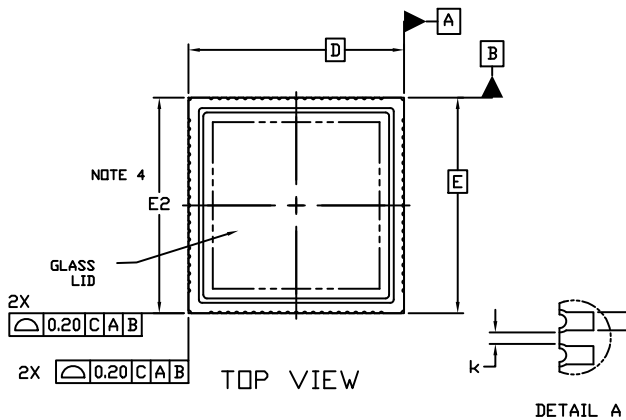**LCC84, 19x19**
CASE 115BC
ISSUE A

DATE 26 JUN 2015

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID IS DEFINED BY DIMENSIONS D2 AND E2 AND HAS A MAXIMUM ALLOWABLE SHIFT OF 0.60 BEYOND DIMENSIONS D AND E.

TOP VIEW

DETAIL A

SIDE VIEW

BOTTOM VIEW

DIM	MILLIMETERS	
	MIN.	MAX.
A	2.08	2.74
A2	1.78 REF	
A3	0.55 REF	
b	0.32	0.48
D	19.00 BSC	
D2	19.00 REF	
E	19.00 BSC	
E2	19.00 REF	
e	0.75 BSC	
k	0.12	---
L	0.62	0.88
L1	1.00 REF	
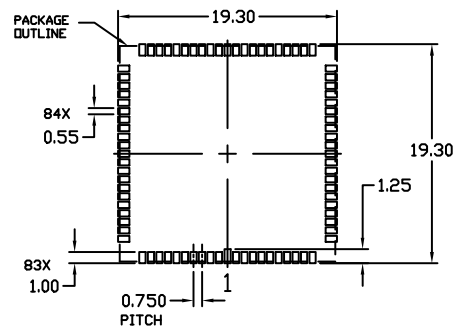
GENERIC MARKING DIAGRAM

XXXXXXXXXXXX
XXXX
AWLYYWW
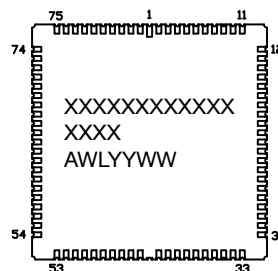
XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

RECOMMENDED MOUNTING FOOTPRINT

DOCUMENT NUMBER:	98AON82963F	
DESCRIPTION:	LCC84, 19.00 X 19.00	PAGE 1 OF 1